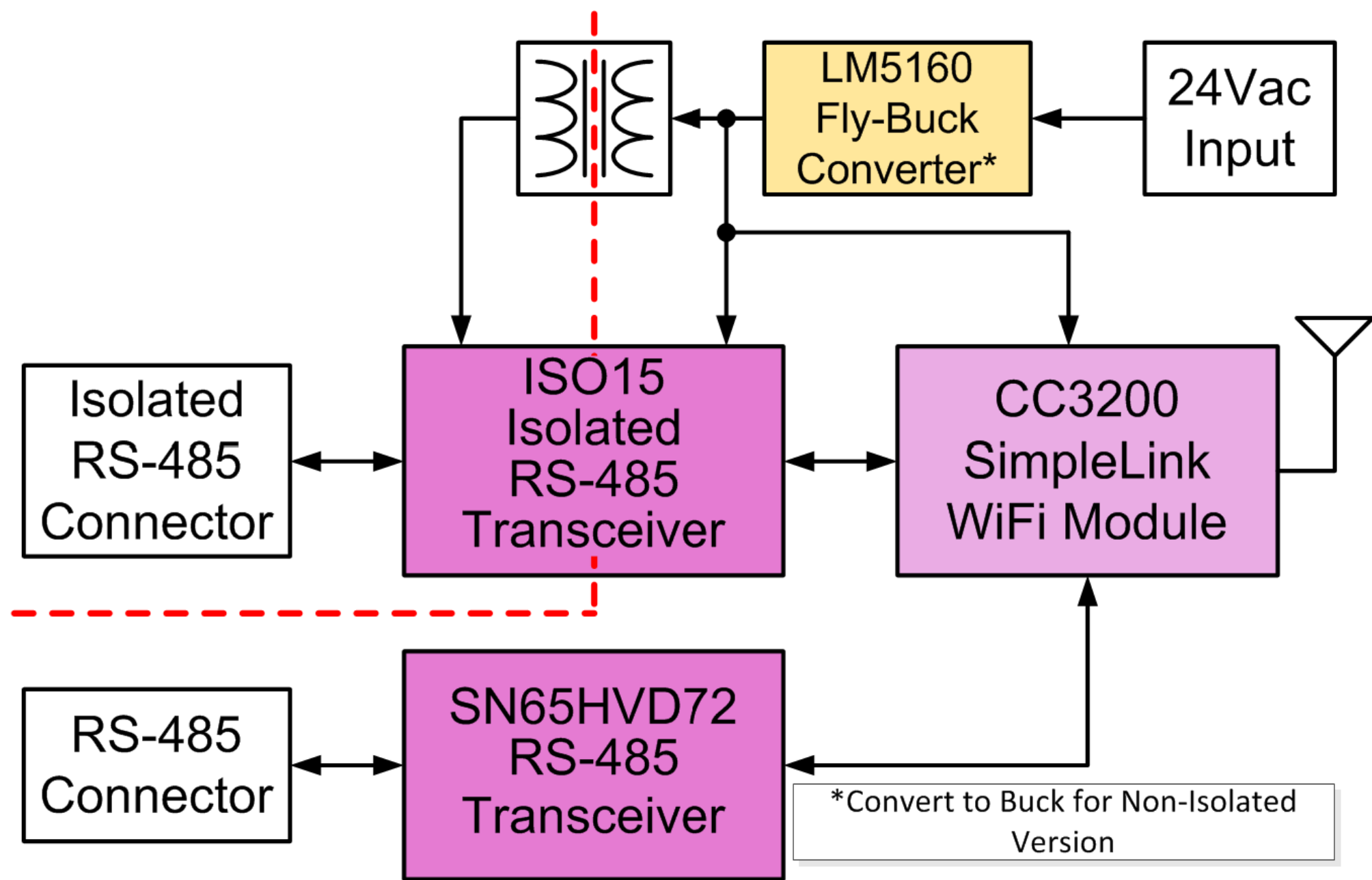
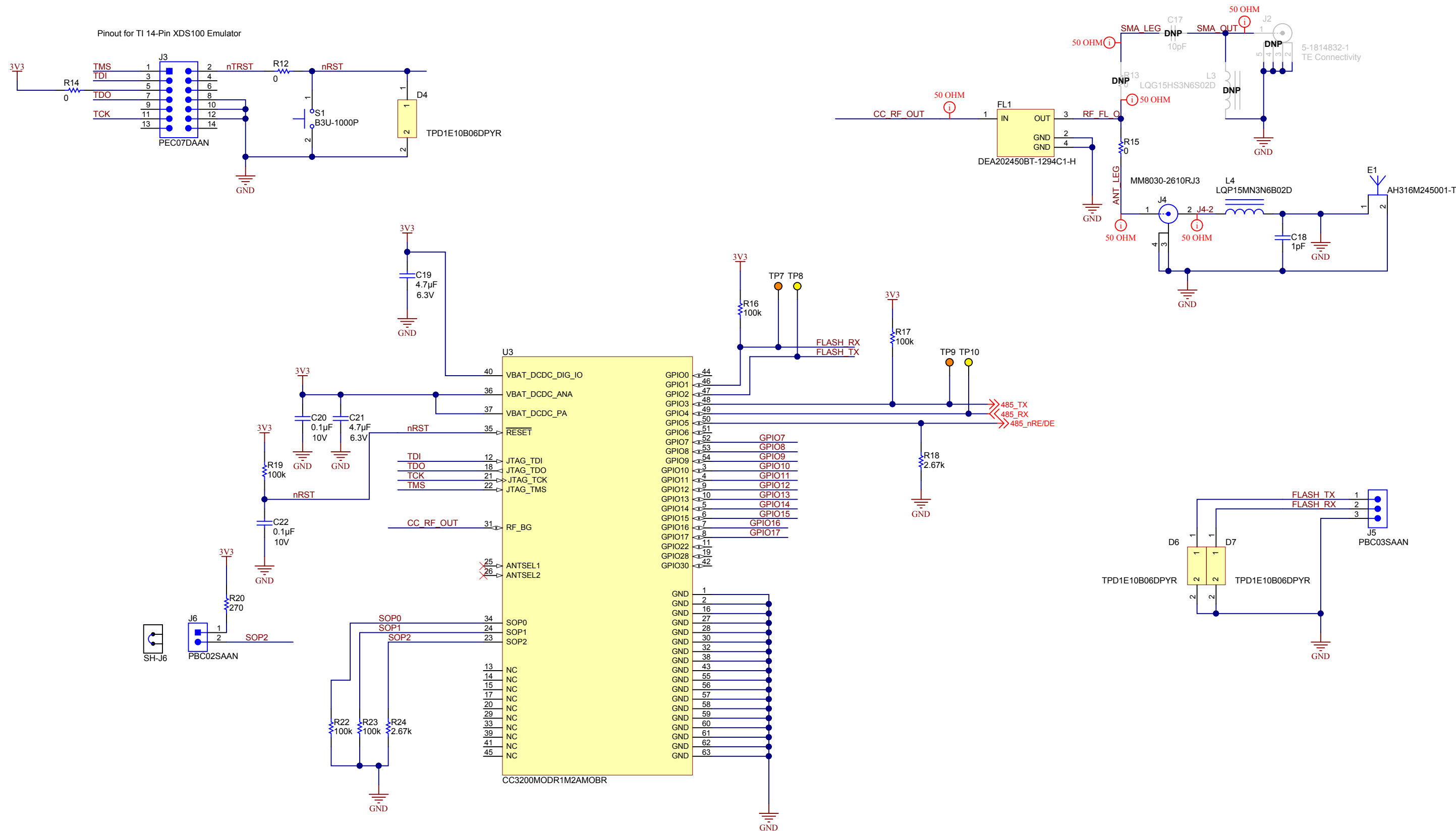


Revision History	
Revision	Notes
E1	Initial Engineering Release. Split ISE4033 from ISE4037 For Clarity in TI Designs



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TID #: TIDA-00486	Project Title: Isolated RS-485 To Wi-Fi Bridge with 24 VAC Power		
Number: ISE4033	Rev: E1	Sheet: 1 of 6	
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B	
Drawn By:	File: ISE4033_ISO485_to_WiFi_Sheet1.SchDoc	Contact: http://www.ti.com/support	
Engineer: M. Knapp			

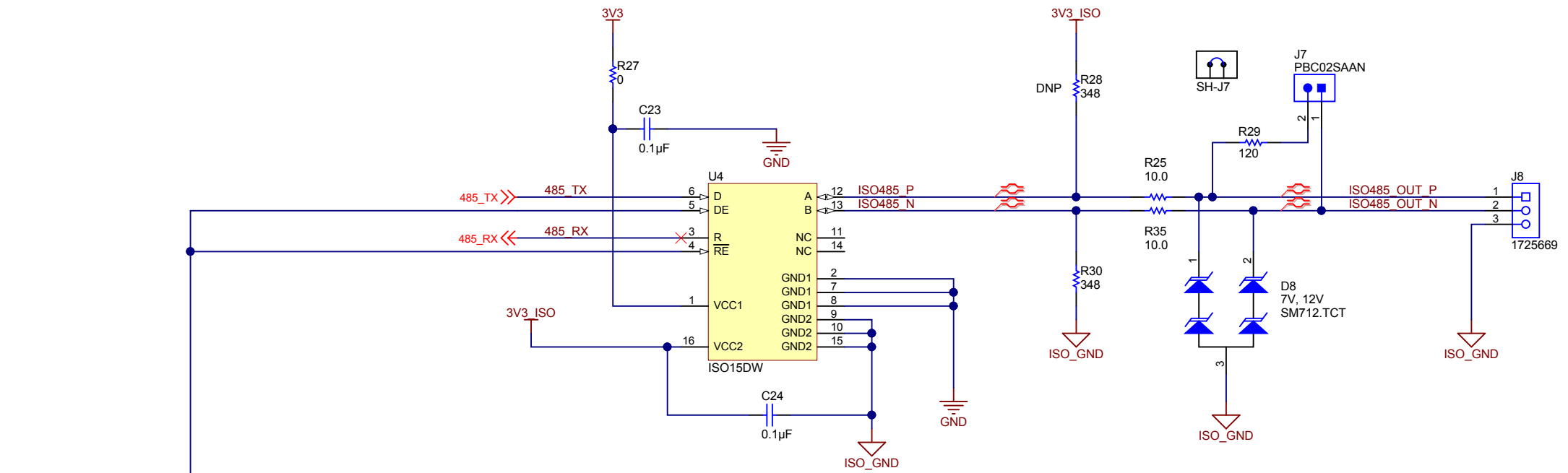


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TID #: TIDA-00486	Project Title: Isolated RS-485 To Wi-Fi Bridge with 24 VAC Power	
Number: ISE4033	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 6
Drawn By:	File: ISE4033_ISO485_to_WiFi_Sheet3.SchDoc	Size: B
Engineer: M. Knapp	Contact: http://www.ti.com/support	

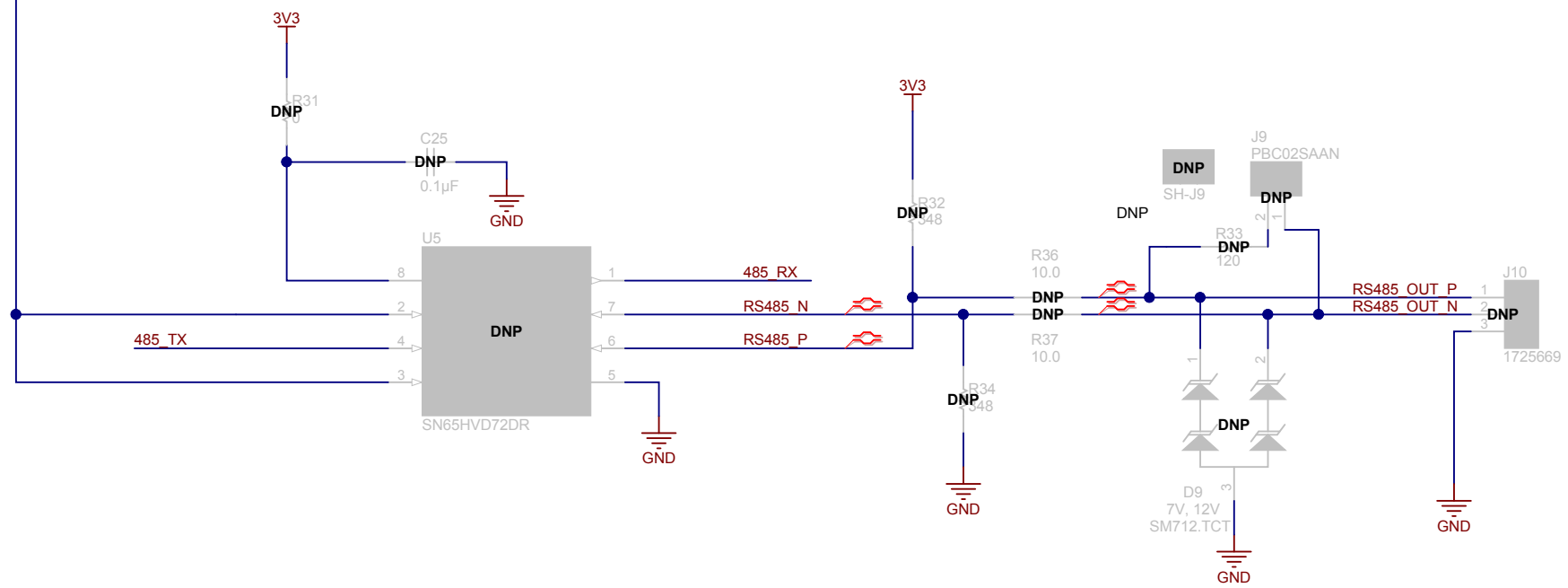
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TID #: TIDA-00486	Project Title: Isolated RS-485 To Wi-Fi Bridge with 24 VAC Power	
Number: ISE4033	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 4 of 6
Drawn By:	File: ISE4033_ISO485_to_WiFi_Sheet4.SchDoc	Size: B
Engineer: M. Knapp	Contact: http://www.ti.com/support	



H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

DNP FID1 DNP FID2 DNP FID3

PCB Number: ISE4033
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

PCB LOGO
CAUTION. READ USER GUIDE BEFORE USE


Label Table	
Variant	Label Text
001	Serial Number
002	Serial Number

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ4
Assembly Note
Place SH-J6 on J6, SH-J7 on J7, and SH-J9 on J9

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TID #: TIDA-00486	Project Title: Isolated RS-485 To Wi-Fi Bridge with 24 VAC Power		
Number: ISE4033	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 5 of 6	
Drawn By:	File: ISE4033_ISO485_to_WiFi_Sheet5.SchDoc	Size: B	
Engineer: M. Knapp	Contact: http://www.ti.com/support		

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